ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES* International and Pan-American co	ourn, Illinois. All rights re	eserved under both	This docume level parts, t	ent is a declaration he declaration end	n of the substance compasses all low	es within the manufactur ver level materials for wl	er listed item. Note hich the manufactur	: if the item is an a er has engineering	ssembly with lower responsibility.		
IPC Web Site for Information on I http://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier Information											
Company name*	ay name* Company unique ID			Unique ID Authority			Response Date*				
onsemi								2023-06-08			
Contact Name	Title - Contact			Phone - Contact*			Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative*	* Title - Representative]	Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Item	n Number Mfr Item	Mfr Item Name		Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type		
NCV293	CV2931AST-5T3G ANA 100MA 5V LE			2023-06-08		MY1	108.86	mg	Each		
Manufacturing Proccess Information				·		·					
Terminal Plating / Grid Array Material	Ferminal Base Alloy	J-STD-020 MSI	L Rating	Peak Process Body Temperature N		ture Max Time at Peak	Temperature Nun	nber of Reflow Cy	cles		
Matte Tin (Sn) - annealed CU Alloy 1				260	С	30	seconds 3				
Comments											
evel 1 - maximum time at peak temperature during so	Idering is 10-30 seconds	5									
For more information regarding material composition	please refer to page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).								
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted				
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all				
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the				
Supplier Digital Signature Ra	stislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.1	mg	Supplier	Silicon (Si)	7440-21-3		1.1	mg
Die Attach	0.74	mg		Epoxy resin	proprietary data		0.0185	mg
			Supplier	Silver (Ag)	7440-22-4		0.6253	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0185	mg
			Supplier	Inorganic filler	Proprietary Data		0.0185	mg
			Supplier	Dicyandiamine	461-58-5		0.0037	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.0555	mg
Lead Frame	37.17	mg	Supplier	Silver (Ag)	7440-22-4		0.4832	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0372	mg
			Supplier	Iron (Fe)	7439-89-6		0.8921	mg
			Supplier	Copper (Cu)	7440-50-8		35.7575	mg
Mold Compound-Black	62.4	2.4 mg		Epoxy resin	proprietary data		3.12	mg
			Supplier	Phenolic Resin	Proprietary Data		3.12	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.248	mg
			Supplier	Carbon Black (C)	1333-86-4		0.312	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		54.6	mg
Plating	7.44	mg	Supplier	Tin (Sn)	7440-31-5		7.44	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg